

L Number	Hits	Search Text	DB	Time stamp
-	150	(73/204.22).CCLS.	USPAT; US-PGPUB; EPO; JPO	2003/02/26 15:59
-	0	("18 and semiconductor").PN.	USPAT; US-PGPUB; EPO; JPO	2002/09/30 14:01
-	24	((73/204.22).CCLS.) and semiconductor	USPAT; US-PGPUB; EPO; JPO	2002/09/30 14:02
-	16	((73/204.22).CCLS.) and semiconductor) and (seal\$4 ring)	USPAT; US-PGPUB; EPO; JPO	2002/09/30 14:03
-	15	((73/204.22).CCLS.) and semiconductor) and (seal\$4 ring)) and (housing enclosure body fixture)	USPAT; US-PGPUB; EPO; JPO	2002/09/30 14:05
-	1	("6351390").PN.	USPAT; US-PGPUB; EPO; JPO	2002/09/30 15:07
-	10713	"flow sensor"	USPAT; US-PGPUB; EPO; JPO	2002/09/30 18:27
-	2660	"flow sensor" and housing	USPAT; US-PGPUB; EPO; JPO	2002/09/30 15:07
-	6	("flow sensor" and housing) and semiconductor) and (seal\$4 ring) near4 semiconductor	USPAT; US-PGPUB; EPO; JPO	2002/09/30 15:30
-	0	20020043710.URPN.	USPAT	2002/09/30 15:08
-	0	5871627.URPN.	USPAT	2002/09/30 15:12
-	0	5871627.URPN.	USPAT	2002/09/30 15:12
-	3277	"strip conductor"	USPAT; US-PGPUB; EPO; JPO	2002/09/30 15:31
-	7	("strip conductor" and 73/\$7.ccls.) and semiconductor	USPAT; US-PGPUB; EPO; JPO	2002/09/30 16:19
-	52	"strip conductor" and 73/\$7.ccls.	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:49
-	36	("strip conductor" and 73/\$7.ccls.) and spac\$3	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:49
-	19	("strip conductor" and 73/\$7.ccls.) and spac\$3) and force	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:49
-	39	("flow sensor" and housing) and semiconductor) and (glue paste)	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:56
-	102	("flow sensor" and housing) and (ridg\$3 bump tip) near4 (housing enclosure chamber body plate mount\$4)	USPAT; US-PGPUB; EPO; JPO	2002/09/30 18:29
-	26	("flow sensor" and housing) and (ridg\$3 bump tip) near4 (housing enclosure chamber body plate mount\$4)) and (semiconductor silicon)	USPAT; US-PGPUB; EPO; JPO	2002/09/30 18:29
-	377	("flow sensor" and housing) and semiconductor	USPAT; US-PGPUB; EPO; JPO	2002/09/30 18:52
-	942	(73/202,204.15,204.16,204.22,204.26).CCLS.	USPAT; US-PGPUB; EPO; JPO	2003/02/26 15:59
-	2	((73/202,204.15,204.16,204.22,204.26).CCLS.) and "semiconductor chip") and (seal\$5 O) near3 ring	USPAT; US-PGPUB; EPO; JPO	2003/02/26 16:02

-	30	((73/202,204.15,204.16,204.22,204.26).CCLS.) and "semiconductor chip"	USPAT; US-PGPUB; EPO; JPO	2003/02/27 09:42
-	7	((73/202,204.15,204.16,204.22,204.26).CCLS.) and "semiconductor chip") and seal\$4	USPAT; US-PGPUB; EPO; JPO	2003/02/27 11:08
-	1	("4548078").PN.	USPAT; US-PGPUB; EPO; JPO	2003/02/27 11:08

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